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| <b>Notice of References Cited</b> | Application/Control No.<br>10/613,459 | Applicant(s)/Patent Under<br>Reexamination<br>FREY ET AL. |             |
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|   | E | US-  |                 |           |                |
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.